Application No. 10/750,342 Amendment dated January 29, 2008 Reply to Office Action of August 8, 2007

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously presented) A method for determining an operating parameter of a chip having first and second ring oscillators, comprising:

measuring a frequency of the first ring oscillator;

measuring a frequency of the second ring oscillator; and

calculating an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

2. (Original) The method of claim 1 wherein the measuring of the first ring oscillator frequency comprises:

obtaining two ring oscillator clock counts, separated by a time difference, from a ring oscillator;

obtaining two independent clock counts, separated by the time differences, from a clock output independent from the ring oscillator; and

calculating a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

- 3. Canceled.
- 4. Canceled.
- 5. (Previously presented) The method of claim 1, further comprising:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's actual temperature.

6. (Previously presented) The method of claim 33, further comprising:

dividing the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's process speed.

7. (Previously presented) The method of claim 6, further comprising:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determining, as a function of the second result and the characterization data, the chip's actual temperature; and

adjusting the determined process speed according to the determined actual temperature.

8. (Previously presented) The method of claim 1, further comprising:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determining, from the comparison, the actual temperature of the chip.

9. (Previously presented) The method of claim 33, further comprising:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency numbers relative to process speed; and

determining, from the comparison, the process speed of the chip.

10. (Previously presented) Computer-readable media embodying a program of instructions executable by a computer to perform a method of determining an operating parameter of a chip having first and second ring oscillators, the method comprising:

measuring a frequency of the first ring oscillator;

measuring a frequency of the second ring oscillator; and

calculating an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

11. (Original) The computer-readable media of claim 10 wherein the measuring of the first ring oscillator frequency comprises:

obtaining two ring oscillator clock counts, separated by a time difference, from a ring oscillator;

obtaining two independent clock counts, separated by the time difference, from a clock output independent of the ring oscillator; and

calculating a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

- 12. Canceled.
- 13. Canceled.

14. (Previously presented) The computer-readable media of claim 10, wherein the method further comprises:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's actual temperature.

15. (Previously presented) The computer-readable media of claim 34, wherein the method further comprises:

dividing the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's process speed.

16. (Previously presented) The computer-readable media of claim 15, wherein the method further comprises:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determining, as a function of the second result and the characterization data, the chip's actual temperature; and

adjusting the determined process speed according to the determined actual temperature.

17. (Previously presented) The computer-readable media of claim 10, wherein the method further comprises:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determining, from the comparison, the actual temperature of the chip.

18. (Previously presented) The computer-readable media of claim 34, wherein the method of further comprises:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency numbers relative to process speed; and

determining, from the comparison, the process speed of the chip.

19. (Previously presented) A system comprising:

a chip having first and second ring oscillators; and

a processor configured to:

measure a frequency of the first ring oscillator;

measure a frequency of the second ring oscillator; and

calculate an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

- 20. (Original) The system of claim 19 wherein the chip comprises the processor.
- 21. (Original) The system of claim 19 wherein the processor is separate from but operably connected to the chip.
  - 22. (Original) The system of claim 19 wherein the chip additionally comprises:

a first counter configured to obtain two ring oscillator clock counts, separated by a time difference, from the first ring oscillator;

a second counter configured to obtain two independent clock counts, separated by the time difference, from a clock output independent of the first and second ring oscillators; and

wherein the processor is further configured to calculate a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

- 23. Canceled.
- 24. Canceled.
- 25. (Previously presented) The system of claim 19, wherein the processor is additionally configured to:

multiply the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determine, as a function of the result and characterization data of the chip, the chip's actual temperature.

26. (Previously presented) The system of claim 35, wherein the processor is additionally configured to:

divide the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determine, as a function of the result and characterization data of the chip, the chip's process speed.

27. (Previously presented) The system of claim 26, wherein the processor is further configured to:

multiply the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determine, as a function of the second result and the characterization data, the chip's actual temperature; and

adjust the determined process speed according to the determined actual temperature.

28. (Previously presented) The system of claim 19, wherein the processor is further configured to:

calculate a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

compare the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determine, from the comparison, the actual temperature of the chip.

29. (Previously presented) The system of claim 35, wherein the processor is further configured to:

calculate a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

compare the calculated scaled frequency value with a known rang of scaled frequency numbers relative to process speed; and

determine, from the comparison, the process speed of the chip.

30. (Previously presented) A processor comprising:

means for measuring a frequency of a first ring oscillator;

means for measuring a frequency of the second ring oscillator; and

means for calculating an actual temperature of a chip as a function of the first and second ring oscillator frequencies.

- 31. Canceled.
- 32. Canceled.
- 33. (Previously presented) The method of claim 1 further comprising determining a process speed of the chip in response to the actual temperature.
- 34. (Currently amended) The method media of claim 10 further comprising determining a process speed of the chip in response to the actual temperature.
- 35. (Currently amended) The method system of claim 19 wherein the processor is further configured to determine a process speed of the chip in response to the actual temperature.
- 36. (Currently amended) The method processor of claim 30 further comprising means for determining a process speed of the chip in response to the actual temperature.